LNJ812W86RA1

Hight Bright Surface Mounting Chip LED

TSS Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	55	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

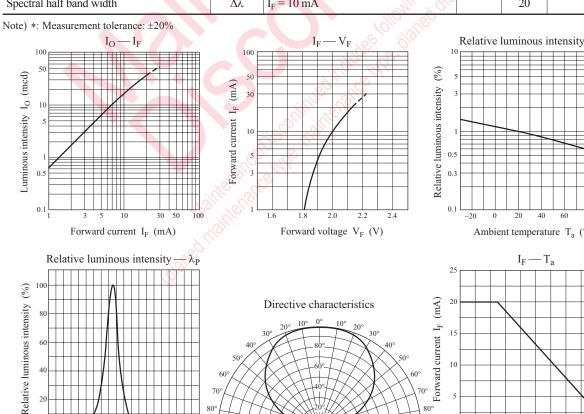
Lighting Color

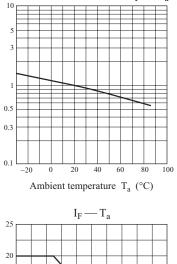
• Soft Orange

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	I _O	$I_{\rm F} = 10 {\rm mA}$	7.9	16.0	44.6	mcd
Reverse current	I _R	$V_R = 4 V$			100	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$	dur,	2.0	2.5	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_F = 10 \text{ mA}$	1 all	615		nm
Dominant emission wavelength	λ_d	$I_{\rm F} = 10 \mathrm{mA}$	ollin.	605		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		20		nm





0 × 0

20

40

60

Ambient temperature T_a (°C)

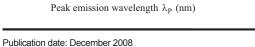
80

100

909

60

80 100 Ľ



700

550

600

650

90.9

100 80 60 40

0

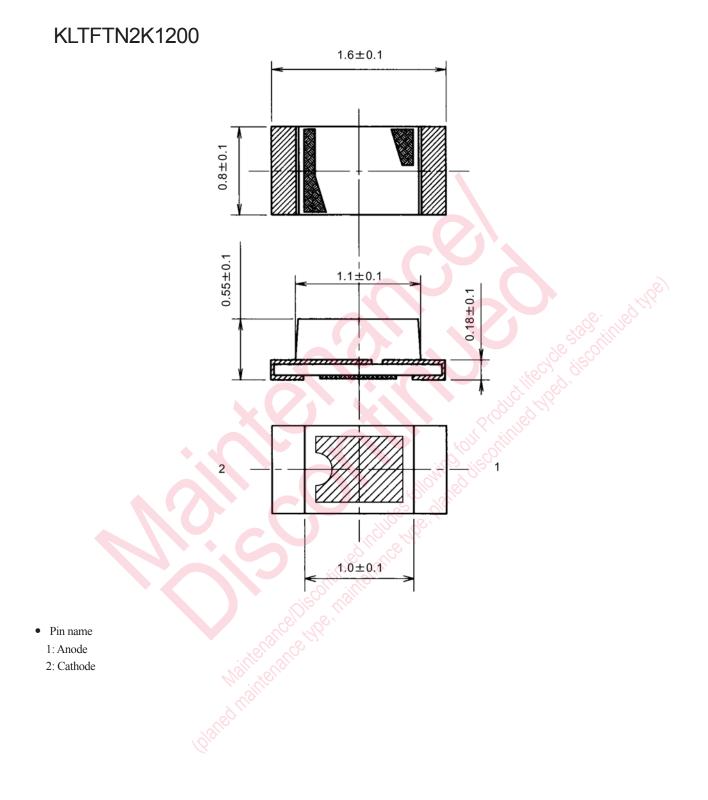
Relative luminous intensity (%)

20 40

20

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Package (Unit: mm)



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